

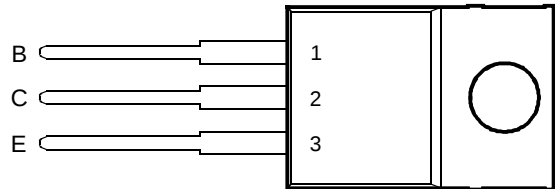
BDX33, BDX33A, BDX33B, BDX33C, BDX33D NPN SILICON POWER DARLINGTONS

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AUGUST 1993 - REVISED MARCH 1997

- Designed for Complementary Use with BDX34, BDX34A, BDX34B, BDX34C and BDX34D
- 70 W at 25°C Case Temperature
- 10 A Continuous Collector Current
- Minimum h_{FE} of 750 at 3 V, 3 A

TO-220 PACKAGE
(TOP VIEW)



Pin 2 is in electrical contact with the mounting base.

MDTRACA

absolute maximum ratings at 25°C case temperature (unless otherwise noted)

RATING		SYMBOL	VALUE	UNIT
Collector-base voltage ($I_E = 0$)	BDX33	V_{CBO}	45	V
	BDX33A		60	
	BDX33B		80	
	BDX33C		100	
	BDX33D		120	
Collector-emitter voltage ($I_B = 0$)	BDX33	V_{CEO}	45	V
	BDX33A		60	
	BDX33B		80	
	BDX33C		100	
	BDX33D		120	
Emitter-base voltage		V_{EBO}	5	V
Continuous collector current		I_C	10	A
Continuous base current		I_B	0.3	A
Continuous device dissipation at (or below) 25°C case temperature (see Note 1)		P_{tot}	70	W
Continuous device dissipation at (or below) 25°C free air temperature (see Note 2)		P_{tot}	2	W
Operating free air temperature range		T_J	-65 to +150	°C
Storage temperature range		T_{stg}	-65 to +150	°C
Operating free-air temperature range		T_A	-65 to +150	°C

NOTES: 1. Derate linearly to 150°C case temperature at the rate of 0.56 W/°C.
2. Derate linearly to 150°C free air temperature at the rate of 16 mW/°C.

PRODUCT INFORMATION

Information is current as of publication date. Products conform to specifications in accordance with the terms of Power Innovations standard warranty. Production processing does not necessarily include testing of all parameters.



BDX33, BDX33A, BDX33B, BDX33C, BDX33D

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electrical characteristics at 25°C case temperature (unless otherwise noted)

PARAMETER	TEST CONDITIONS				MIN	TYP	MAX	UNIT
$V_{(BR)CEO}$ Collector-emitter breakdown voltage	$I_C = 100 \text{ mA}$	$I_B = 0$	(see Note 3)	BDX33 BDX33A BDX33B BDX33C BDX33D	45 60 80 100 120			V
I_{CEO} Collector-emitter cut-off current	$V_{CE} = 30 \text{ V}$ $V_{CE} = 30 \text{ V}$ $V_{CE} = 40 \text{ V}$ $V_{CE} = 50 \text{ V}$ $V_{CE} = 60 \text{ V}$ $V_{CE} = 30 \text{ V}$ $V_{CE} = 30 \text{ V}$ $V_{CE} = 40 \text{ V}$ $V_{CE} = 50 \text{ V}$ $V_{CE} = 60 \text{ V}$	$I_B = 0$ $I_B = 0$ $I_B = 0$ $I_B = 0$ $I_B = 0$ $I_B = 0$ $I_B = 0$ $I_B = 0$ $I_B = 0$ $I_B = 0$	$T_C = 100^\circ\text{C}$ $T_C = 100^\circ\text{C}$ $T_C = 100^\circ\text{C}$ $T_C = 100^\circ\text{C}$ $T_C = 100^\circ\text{C}$	BDX33 BDX33A BDX33B BDX33C BDX33D BDX33 BDX33A BDX33B BDX33C BDX33D			0.5 0.5 0.5 0.5 0.5 10 10 10 10 10	mA
I_{CBO} Collector cut-off current	$V_{CB} = 45 \text{ V}$ $V_{CB} = 60 \text{ V}$ $V_{CB} = 80 \text{ V}$ $V_{CB} = 100 \text{ V}$ $V_{CB} = 120 \text{ V}$ $V_{CB} = 45 \text{ V}$ $V_{CB} = 60 \text{ V}$ $V_{CB} = 80 \text{ V}$ $V_{CB} = 100 \text{ V}$ $V_{CB} = 120 \text{ V}$	$I_E = 0$ $I_E = 0$ $I_E = 0$ $I_E = 0$ $I_E = 0$ $I_E = 0$ $I_E = 0$ $I_E = 0$ $I_E = 0$ $I_E = 0$	$T_C = 100^\circ\text{C}$ $T_C = 100^\circ\text{C}$ $T_C = 100^\circ\text{C}$ $T_C = 100^\circ\text{C}$ $T_C = 100^\circ\text{C}$	BDX33 BDX33A BDX33B BDX33C BDX33D BDX33 BDX33A BDX33B BDX33C BDX33D			1 1 1 1 1 5 5 5 5 5	mA
I_{EBO} Emitter cut-off current	$V_{EB} = 5 \text{ V}$	$I_C = 0$					10	mA
h_{FE} Forward current transfer ratio	$V_{CE} = 3 \text{ V}$ $V_{CE} = 3 \text{ V}$ $V_{CE} = 3 \text{ V}$ $V_{CE} = 3 \text{ V}$ $V_{CE} = 3 \text{ V}$	$I_C = 4 \text{ A}$ $I_C = 4 \text{ A}$ $I_C = 3 \text{ A}$ $I_C = 3 \text{ A}$ $I_C = 3 \text{ A}$	(see Notes 3 and 4)	BDX33 BDX33A BDX33B BDX33C BDX33D	750 750 750 750 750			
$V_{BE(on)}$ Base-emitter voltage	$V_{CE} = 3 \text{ V}$ $V_{CE} = 3 \text{ V}$ $V_{CE} = 3 \text{ V}$ $V_{CE} = 3 \text{ V}$ $V_{CE} = 3 \text{ V}$	$I_C = 4 \text{ A}$ $I_C = 4 \text{ A}$ $I_C = 3 \text{ A}$ $I_C = 3 \text{ A}$ $I_C = 3 \text{ A}$	(see Notes 3 and 4)	BDX33 BDX33A BDX33B BDX33C BDX33D			2.5 2.5 2.5 2.5 2.5	V
$V_{CE(sat)}$ Collector-emitter saturation voltage	$I_B = 8 \text{ mA}$ $I_B = 8 \text{ mA}$ $I_B = 6 \text{ mA}$ $I_B = 6 \text{ mA}$ $I_B = 6 \text{ mA}$	$I_C = 4 \text{ A}$ $I_C = 4 \text{ A}$ $I_C = 3 \text{ A}$ $I_C = 3 \text{ A}$ $I_C = 3 \text{ A}$	(see Notes 3 and 4)	BDX33 BDX33A BDX33B BDX33C BDX33D			2.5 2.5 2.5 2.5 2.5	V
V_{EC} Parallel diode forward voltage	$I_E = 8 \text{ A}$	$I_B = 0$					4	V

NOTES: 3. These parameters must be measured using pulse techniques, $t_p = 300 \mu\text{s}$, duty cycle $\leq 2\%$.

4. These parameters must be measured using voltage-sensing contacts, separate from the current carrying contacts.

PRODUCT INFORMATION

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thermal characteristics

PARAMETER		MIN	TYP	MAX	UNIT
$R_{\theta JC}$	Junction to case thermal resistance			1.78	°C/W
$R_{\theta JA}$	Junction to free air thermal resistance			62.5	°C/W

resistive-load-switching characteristics at 25°C case temperature

PARAMETER	TEST CONDITIONS [†]			MIN	TYP	MAX	UNIT
t_{on} Turn-on time	$I_C = 3\text{ A}$	$I_{B(on)} = 12\text{ mA}$	$I_{B(off)} = -12\text{ mA}$		1		μs
t_{off} Turn-off time	$V_{BE(off)} = -3.5\text{ V}$	$R_L = 10\ \Omega$	$t_p = 20\ \mu\text{s}$, $dc \leq 2\%$		5		μs

[†] Voltage and current values shown are nominal; exact values vary slightly with transistor parameters.

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TYPICAL CHARACTERISTICS

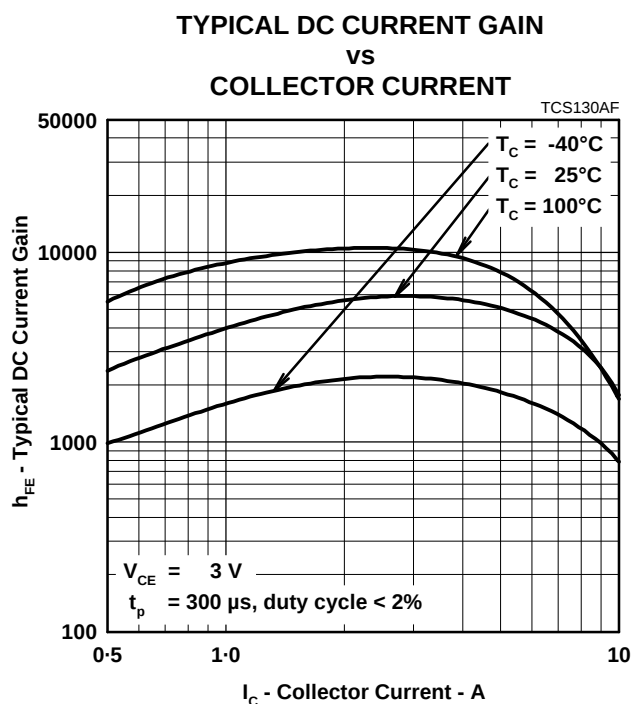


Figure 1.

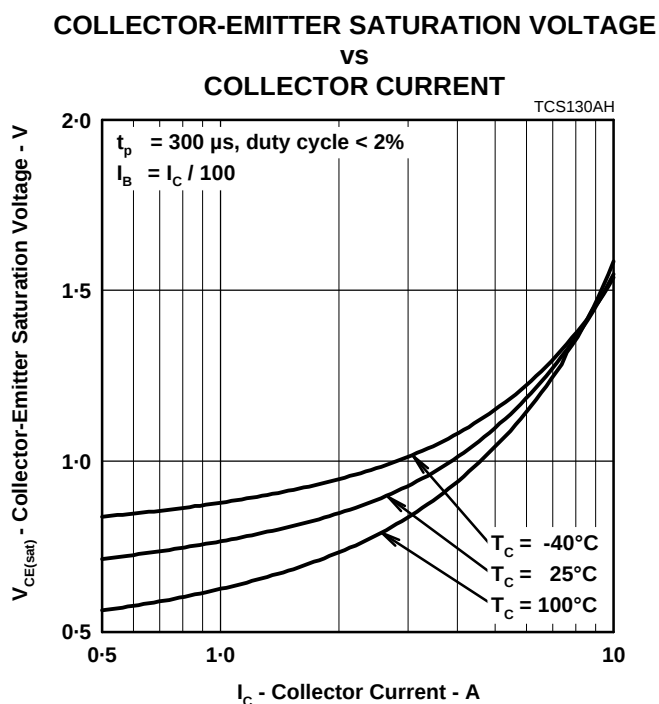


Figure 2.

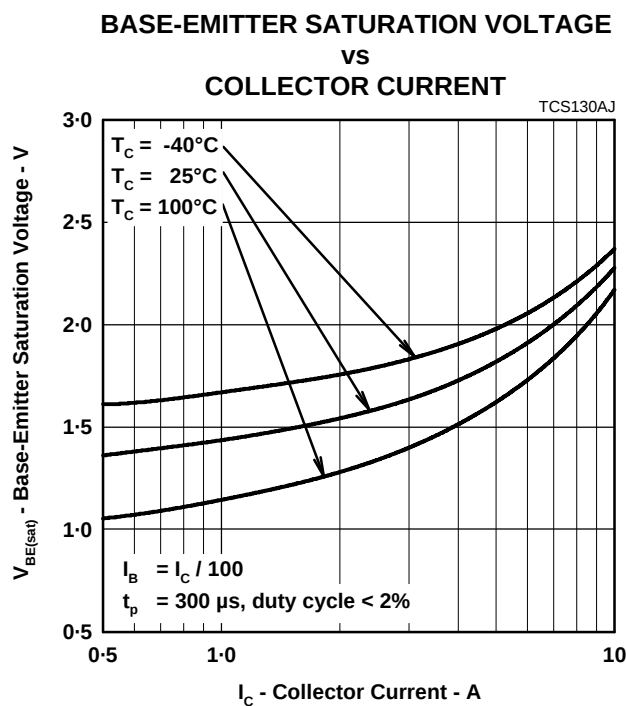


Figure 3.

PRODUCT INFORMATION

THERMAL INFORMATION

MAXIMUM POWER DISSIPATION
VS
CASE TEMPERATURE

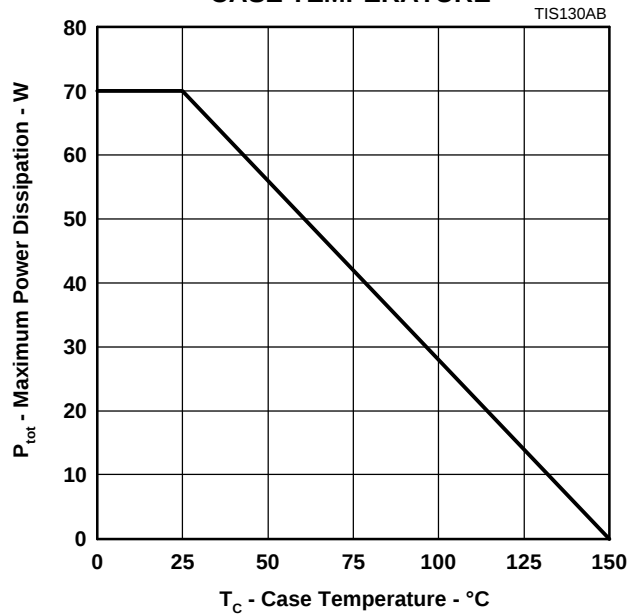


Figure 4.

BDX33, BDX33A, BDX33B, BDX33C, BDX33D NPN SILICON POWER DARLINGTONS

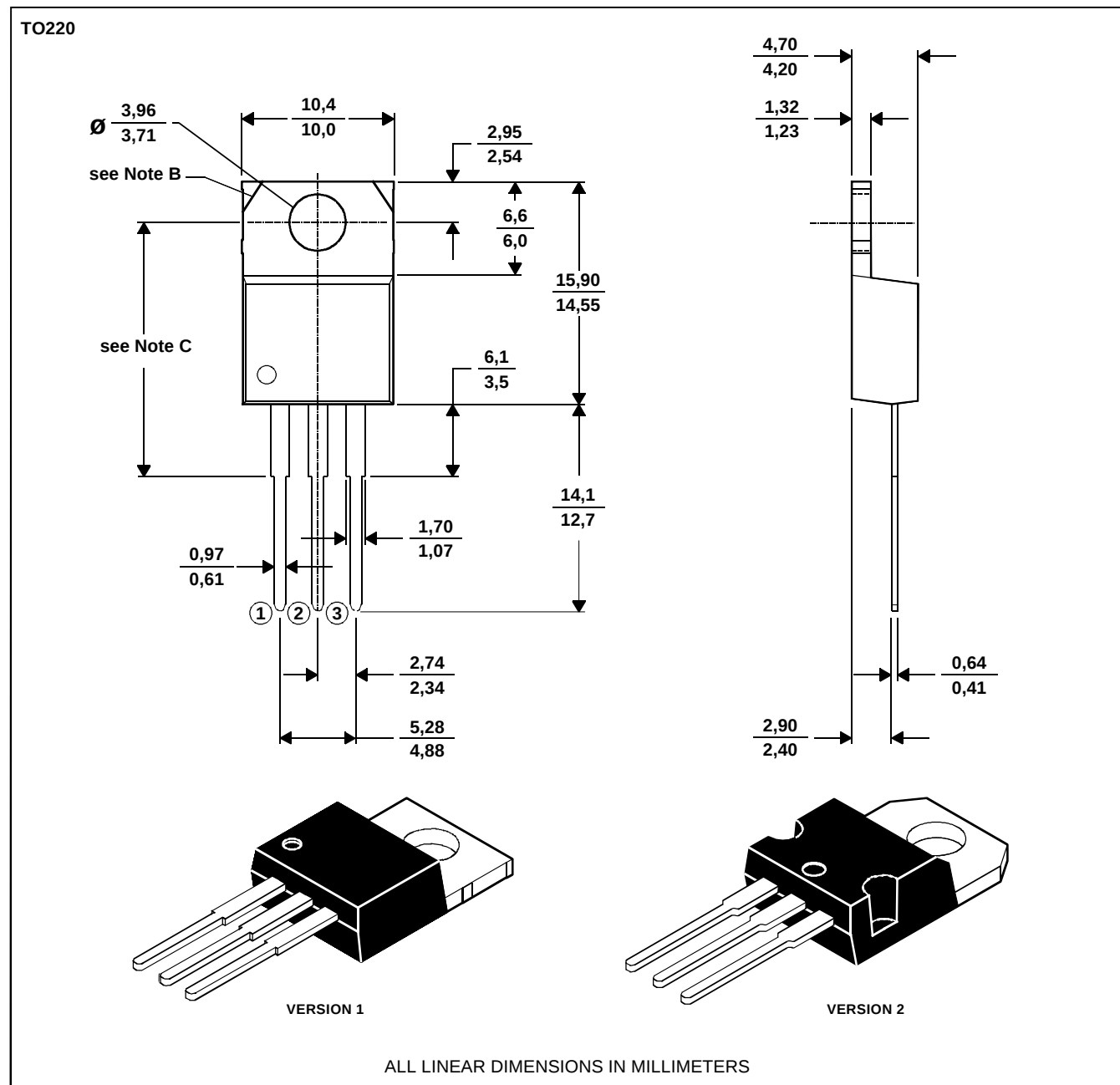
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MECHANICAL DATA

TO-220

3-pin plastic flange-mount package

This single-in-line package consists of a circuit mounted on a lead frame and encapsulated within a plastic compound. The compound will withstand soldering temperature with no deformation, and circuit performance characteristics will remain stable when operated in high humidity conditions. Leads require no additional cleaning or processing when used in soldered assembly.



- NOTES: A. The centre pin is in electrical contact with the mounting tab.
B. Mounting tab corner profile according to package version.
C. Typical fixing hole centre stand off height according to package version.
Version 1, 18.0 mm. Version 2, 17.6 mm.

MDXXBE

PRODUCT INFORMATION

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